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	Non repetitive surge peak on-state current (full cycle , t_p=20ms)	JOCSR23BM	I_{TSM}	3	A
		JOCSR26BM		6	
		JOCSR29BM		9	
		JOCSR2 BM		12	
	junction to case (AC)		$R_{th(j-c)}$	40	/W
Isolation Voltage			V_{iso}	5000	Vrms
Operating Temperature			T_{opr}	-40~110	
Junction Temperature			T_j	125	
Storage Temperature			T_{stg}	-40~125	
Soldering Temperature			T_{sol}	260	
Peak pulse voltage (T_j=25 ; non-repetitive,off-state)			V_{pp}	3	kV

NOTE1: 100μs pulse, 100Hz frequency
NOTE2: AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter			Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage		V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current		I_R	V_R=6V	-	-	1	μA
Output	Peak Off-state Current, Either Direction		I_{DRM}	V_{DRM} / V_{RRM} =600V, I_F=0	-	-	5	μA
			I_{RRM}		-	-	5	
	Peak On-state Voltage, Either Direction	JOCSR23BM	V_{TM}	I_{TM}=0.3A	-	-	1.2	V
		JOCSR26BM		I_{TM}=0.6A	-	-	1.4	
		JOCSR29BM		I_{TM}=0.9A	-	-	1.45	
		JOCSR2 BM		I_{TM}=1.2A	-	-	1.5	
	Critical Rate of Rise of Off-state voltage		dV/dt	V_D=400V, Gate Open I_F=0, T_j=125	1000	-	-	V/μs
	Critical Rate of Rise of Commutating Voltage							

	Holding Current	I_H	V_D=6V	-	-	25	mA
	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	Ω
	Response Time	t_{on}	V_D				

Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

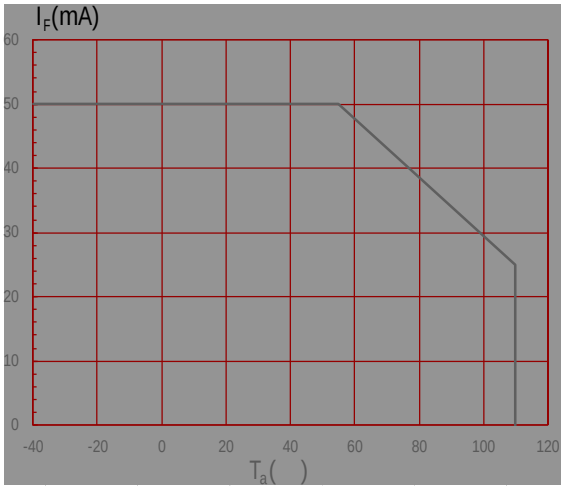


FIG.2: On-state Terminal Current vs. Ambient Temperature

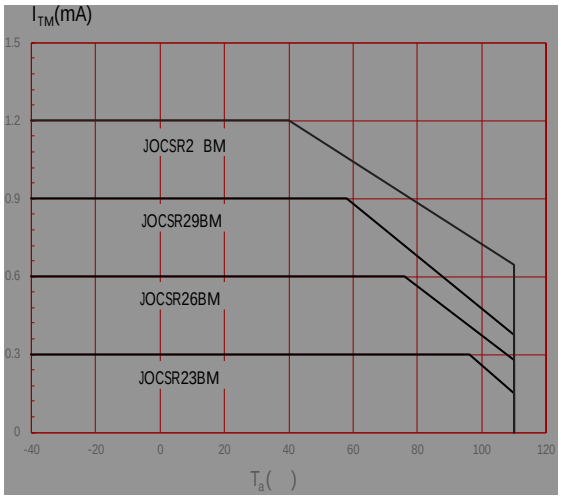


FIG.3: Forward Current vs. Forward Voltage

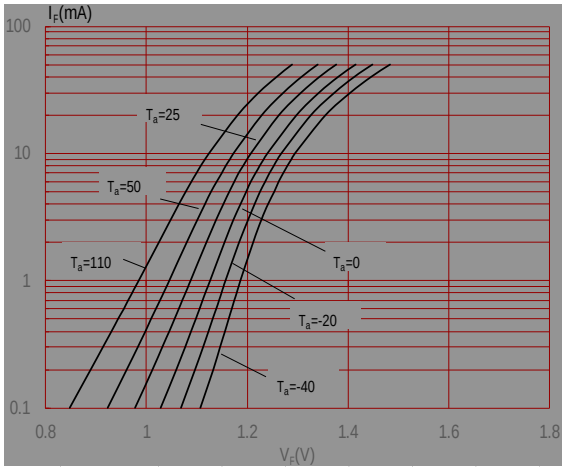


FIG.4: Forward Voltage vs. Ambient Temperature

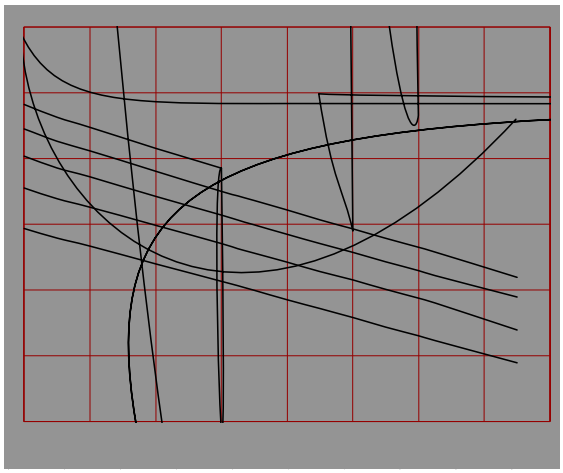


FIG.7: On-state characteristics

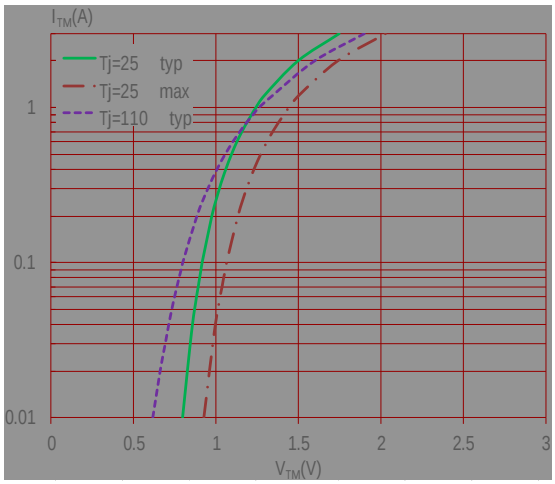
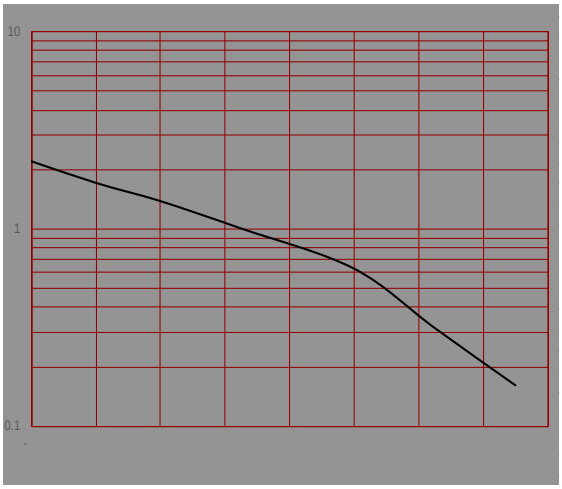


FIG.8: Normalized Holding Current vs. Ambient Temperature



TEST CIRCUITS

FIG.10: Test Circuits of Turn On Time

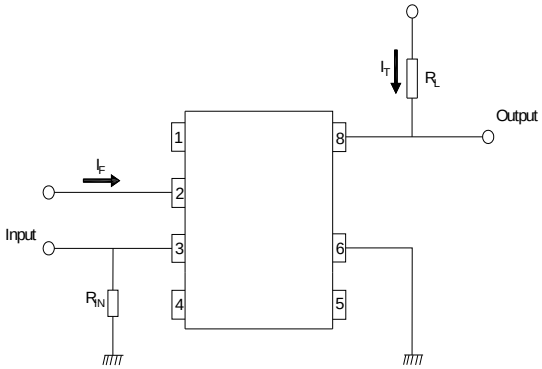
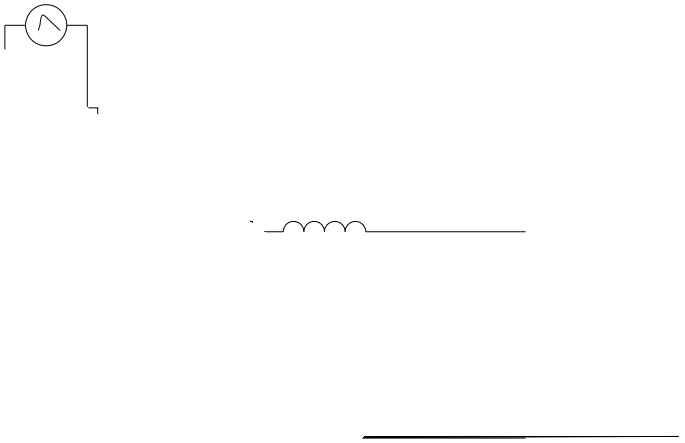
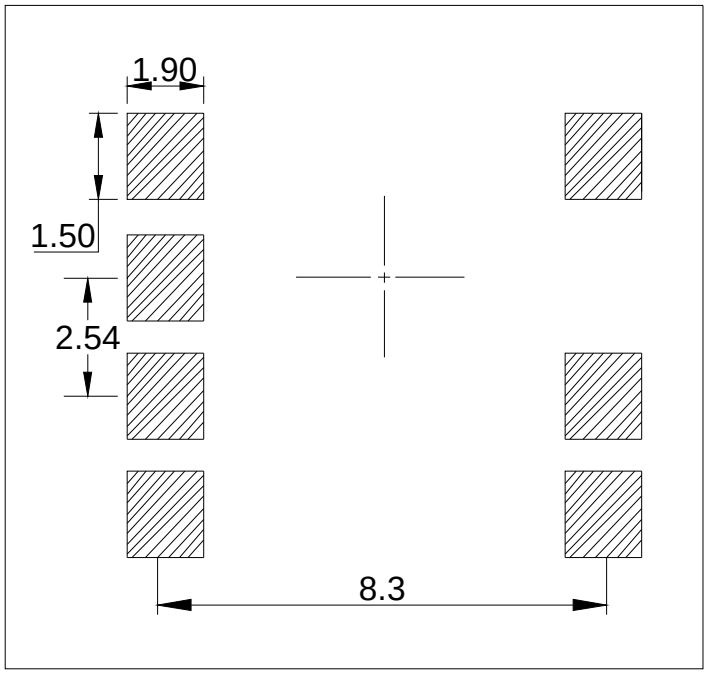


FIG.11: Waveforms of Turn On Time

FIG.12: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards

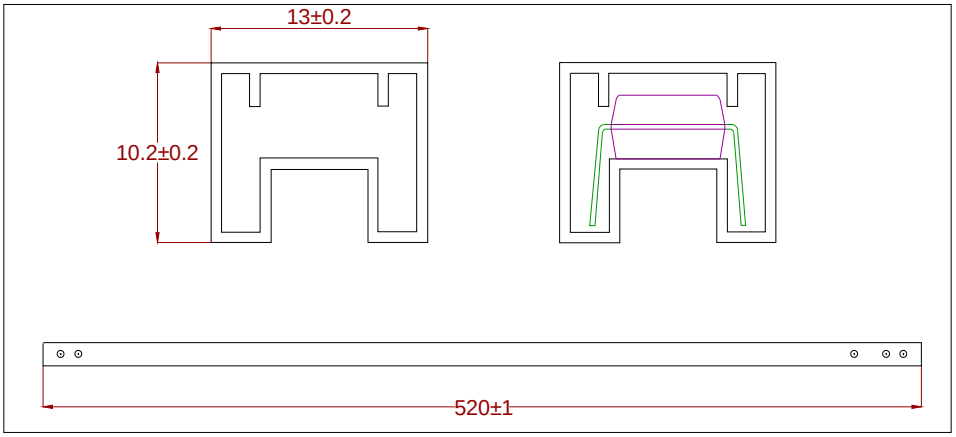


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



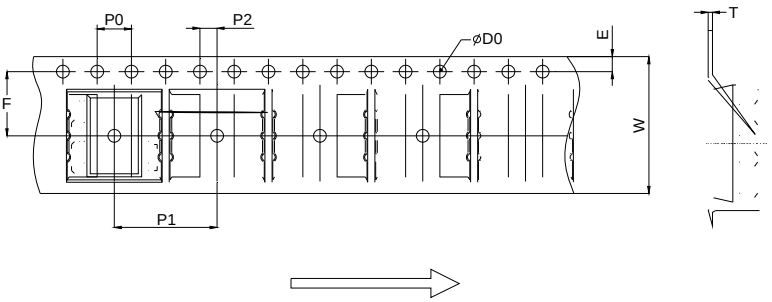
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



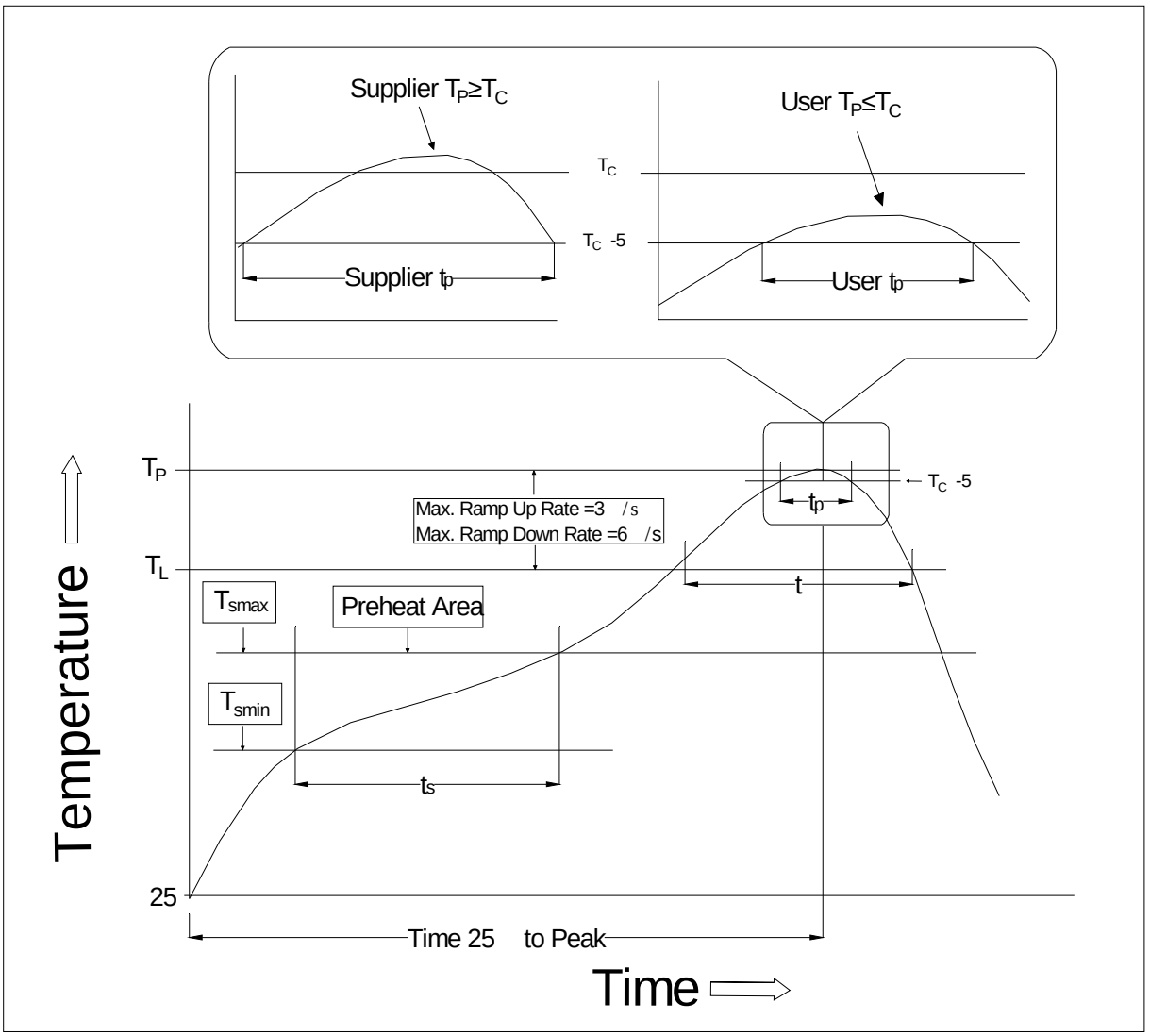
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S/L



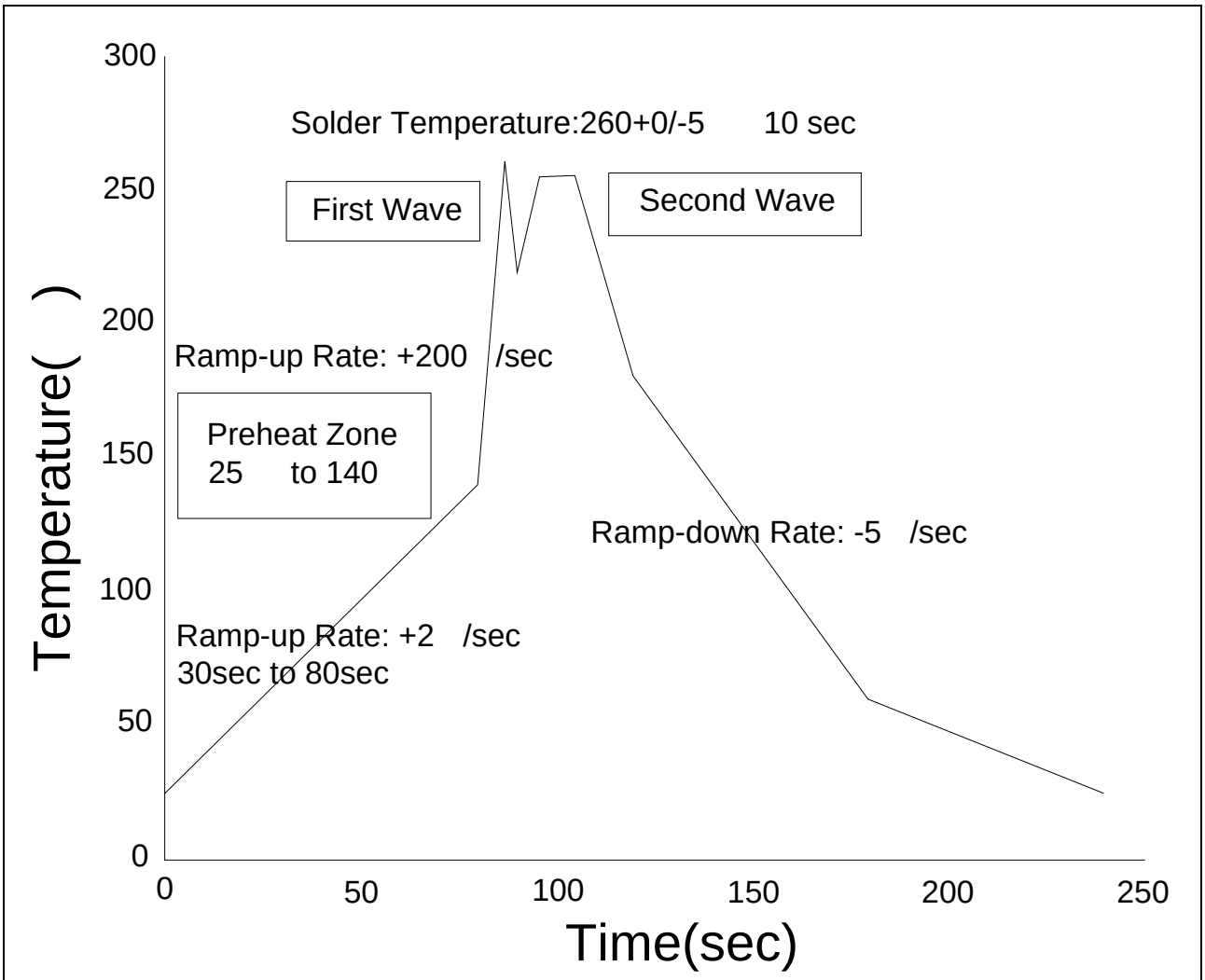
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

REFLOW INFORMATION



Temperature Min. (Tsmin)	150
Temperature Max. (Tsmax)	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.
Liquidous Temperature (TL)	217
Time (tL) Maintained Above (TL)	60-120 seconds
Peak Body Package Temperature	260 +0 /-5
Time (tP) within 5 of 260	10 seconds
Ramp-down Rate (TP to TL)	6 /second max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.